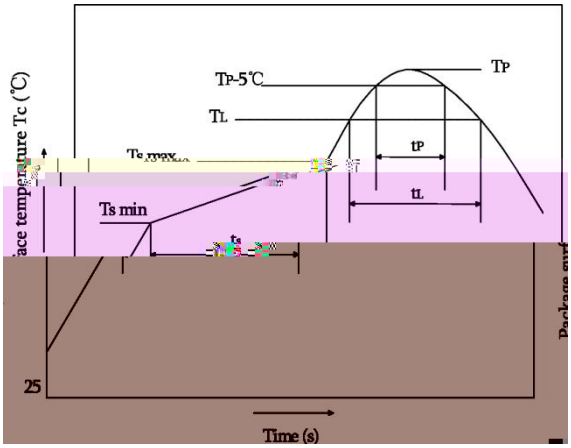
Reflow soldering



	Symbol	Min	Max	Unit
Preheat temperayure	Ts	150	200	
Preheat time	ts	60	120	s
Ramp-up ratea(T_L to T_P)			3	/s
Liquidus temperature	T_L	217		
Time above T_L	t_L	60	150	s
Peak temperature	Tp		260	
Time during which Tc is between (T_P-5) and T_P	t_p		30	s
Ramp-down rate(T_P to T_L)			6	/s

Note:

Wave soldering

Profile feature	
Average ramp-up rate	200 /s
Heating rate during preheat	1 /s to 2 /s typical;4 /s maximum
Final preheat temperature Ts	130
Preheat time (25 to Ts)	60s
Peak temperature Tp	260
Time within peak temperature tp	10s
Ramp-down rate	5 /s maximum

XLM301X,XLM302X,XLM305X